

Description

The AP10N15D uses advanced trench technology to provide excellent R_{DS(ON)}, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

General Features

 $V_{DS} = 150V I_{D} = 10A$

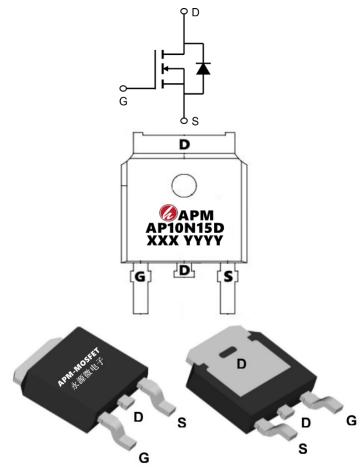
 $R_{DS(ON)} < 285m\Omega@V_{GS}=10V$ (Type: 230m Ω)

Application

Automative lighting

Load switch

Uninterruptible power supply



Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
AP10N15D	TO-252-3L	AP10N15D XXX YYYY	2500

Absolute Maximum Ratings (TC=25 ℃ unless otherwise noted)

Symbol	Parameter	Rating	Units
VDS	Drain-Source Voltage	150	V
VGS	Gate-Source Voltage	±20	V
I _D @T _C =25°C	Drain Current, V _{GS} @ 10V	10	Α
I _D @T _C =100°C	Drain Current, V _{GS} @ 10V	6.1	Α
IDM	Pulsed Drain Current ¹	30	Α
P _D @T _C =25°C	Total Power Dissipation	32.1	W
P _D @T _A =25°C	Total Power Dissipation ³	20.5	W
TSTG	Storage Temperature Range	-55 to 150	°C
TJ	Operating Junction Temperature Range	-55 to 150	°C
RθJA	Maximum Thermal Resistance, Junctionambient	62.5	°C/W
R0JC	Maximum Thermal Resistance, Junction-case	3.9	°C/W



Electrical Characteristics@Tj=25°C(unless otherwise specified)

Symbol	Parameter	Limit		Тур	Max	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	VGS=0V, ID=250μA 1		170		V
VGS(th)	Gate Threshold Voltage	VDS=VGS, ID=250μA	1.2	1.8	2.5	V
IGSS	Gate Leakage Current	VDS=0V, VGS=±20V	S=±20V		±100	nA
IDSS	Zero Gate Voltage Drain Current	VDS=150V, VGS=0V			1	μΑ
RDS(ON)	Drain-Source On-Resistance	VGS=10V, ID= 7A		230	285	mΩ
RDS(ON)	Drain-Source On-Resistance	VGS=4.5V, ID= 6A		250	320	mΩ
VSD	Diode Forward Voltage	Diode Forward Voltage IS=1.8A, VGS=0V		0.8	1.2	٧
Qg	Total Gate Charge			17.5		nC
Qgs	Gate-Source Charge	Gate-Source Charge VDS=75V, VGS=10V, ID=10A		4.5		nC
Qgd	Gate-Drain Charge			4.7		nC
Ciss	Input Capacitance			538		pF
Coss	Output Capacitance	VDS=25V, VGS=0V,f=1MHz		55		pF
Crss	Reverse Transfer Capacitance			21		pF
td(on)	Turn-On Delay Time			11.6		ns
tr	Turn-On Rise Time	VDS=75V, RL =10.68Ω,		9.3		ns
td(off)	Turn-Off Delay Time	VGEN=10V, RG=6Ω		29.3		ns
tf	Turn-Off Fall Time			3.7		ns

Note:

- 1. The data tested by surface mounted on a 1 inch 2 FR-4 board with 2OZ copper.
- $2 \, {}_{\searrow}$ The data tested by pulsed , pulse width $\leqq 300 us$, duty cycle $\leqq 2 \%$
- 3 The EAS data shows Max. rating . The test condition is VDD=72V,VGS=10V,L=0.1mH,IAS=10A
- 4. The power dissipation is limited by 150°C junction temperature
- 5. The data is theoretically the same as I D and I DM, in real applications, should be limited by total power dissipation.



Typical Characteristics

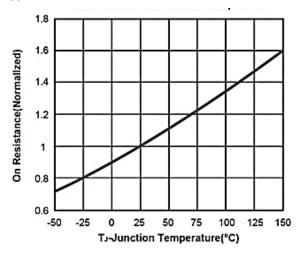


Fig.1 On Resistance Vs Junction Temperature

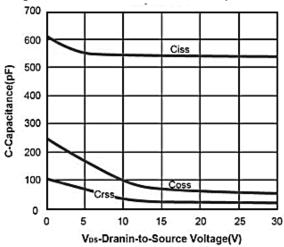


Fig.3 Capacitance

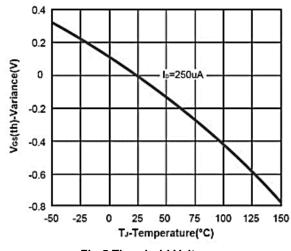


Fig.5 Threshold Voltage

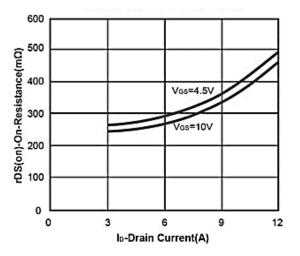


Fig.2 On-Resistance Vs.Drain Current

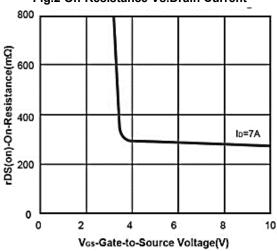


Fig.4 On-Resistance Vs. Gate-to-Sourece Voltage

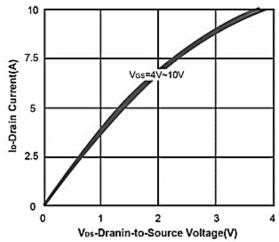
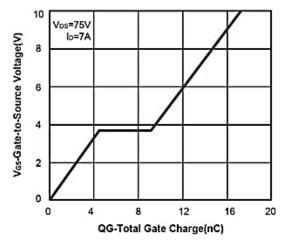


Fig.6 On-Region Characteristics



100

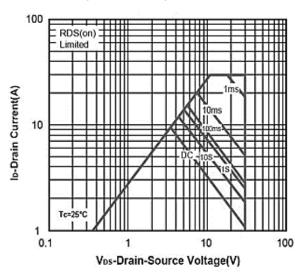


10 0.1 0.2 0.4 0.6 0.8 1 1.2 1.4 1.6 1.8 2

Fig.7 Gate Charge

Fig.8 Body-diode Characteristice

Vsp-Source-to-Drain Voltage(V)





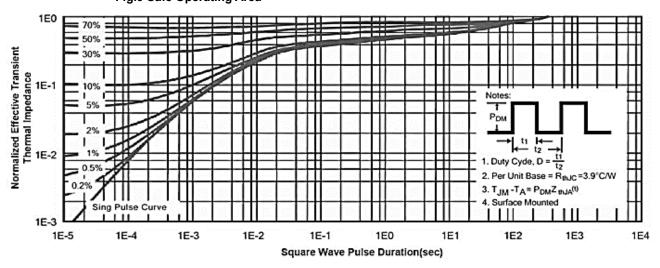
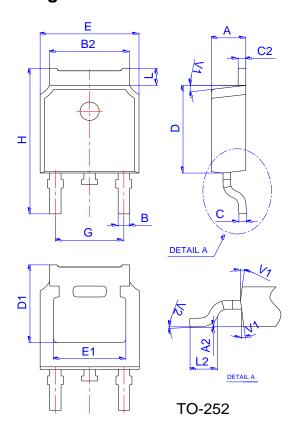


Fig.10 Normalized Maximum Transient Thermal Impedance

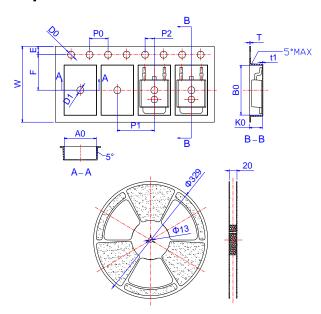


Package Mechanical Data: TO-252-3L



	Dimensions						
Ref.	f. Millin		lillimeters		Inches		
	Min.	Тур.	Max.	Min.	Тур.	Max.	
Α	2.10		2.50	0.083		0.098	
A2	0		0.10	0		0.004	
В	0.66		0.86	0.026		0.034	
B2	5.18		5.48	0.202		0.216	
С	0.40		0.60	0.016		0.024	
C2	0.44		0.58	0.017		0.023	
D	5.90		6.30	0.232		0.248	
D1	5.30REF			0.209REF			
E	6.40		6.80	0.252		0.268	
E1	4.63			0.182			
G	4.47		4.67	0.176		0.184	
Н	9.50		10.70	0.374		0.421	
L	1.09		1.21	0.043		0.048	
L2	1.35		1.65	0.053		0.065	
V1		7°			7°		
V2	0°		6°	0°		6°	

Reel Spectification-TO-252



	Dimensions					
Ref.		Millimeters		Inches		
	Min.	Тур.	Max.	Min.	Тур.	Max.
W	15.90	16.00	16.10	0.626	0.630	0.634
E	1.65	1.75	1.85	0.065	0.069	0.073
F	7.40	7.50	7.60	0.291	0.295	0.299
D0	1.40	1.50	1.60	0.055	0.059	0.063
D1	1.40	1.50	1.60	0.055	0.059	0.063
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	7.90	8.00	8.10	0.311	0.315	0.319
P2	1.90	2.00	2.10	0.075	0.079	0.083
A0	6.85	6.90	7.00	0.270	0.271	0.276
В0	10.45	10.50	10.60	0.411	0.413	0.417
K0	2.68	2.78	2.88	0.105	0.109	0.113
Т	0.24		0.27	0.009		0.011
t1	0.10			0.004		
10P0	39.80	40.00	40.20	1.567	1.575	1.583



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AP10N15D

150V N-Channel Enhancement Mode MOSFET

Edition	Date	Change
Rve1.0	2019/10/29	Initial release
Rve1.1	2021/11/23	Change layout

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